SDAS071B - DECEMBER 1982 - REVISED JANUARY 1995

- Driver Version of 'AS08
- Offers High Capacitive-Drive Capability
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic (N) 300-mil DIPs

description

This device contains four independent 2-input positive-AND buffers/drivers. It <u>performs</u> the Boolean functions $Y = A \cdot B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN74AS1008A is characterized for operation from 0°C to 70°C.

D OR N PACKAGE (TOP VIEW)] v_{cc} 1A 1B 13 4B 2 1Y 12 T 4A 3] 4Y 2A 11 2B ∏ 3B 5 10 2Y 9 3A 6 8 N 3Y GND

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
Н	Н	Н
L	Χ	L
Х	L	L

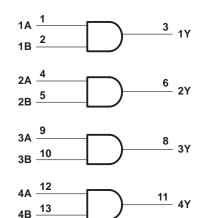
logic symbol†

4B

& ⊳ 3 2 1B 2A 6 5 2B 9 3Δ 10 3B 12 **4A** 11 13

† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7	V
Input voltage, V _I	7	V
Operating free-air temperature range, T _A	0°C to 70°	С
Storage temperature range	-65°C to 150°	С

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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recommended operating conditions†

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
ІОН	High-level output current			-48	mA
I _{OL}	Low-level output current			48	mA
TA	Operating free-air temperature	0		70	°C

[†] This high sink- or source-current device is not recommended for use above 40 MHz.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST COND	ITIONS	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	$I_{\parallel} = -18 \text{ mA}$			-1.2	V
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			
Voн	V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.2		V
	VCC = 4.5 V	$I_{OH} = -48 \text{ mA}$	2	2		
V _{OL}	$V_{CC} = 4.5 V,$	$I_{OL} = 48 \text{ mA}$		0.35	0.5	V
Ι _Ι	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1	mA
lін	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20	μΑ
I _{IL}	$V_{CC} = 5.5 V,$	V _I = 0.4 V			-0.5	mA
I _O §	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-50		-200	mA
ІССН	$V_{CC} = 5.5 V,$	V _I = 4.5 V		5.6	9.5	mA
lccl	$V_{CC} = 5.5 V,$	V _I = 0		13.5	22	mA

switching characteristics (see Figure 1)

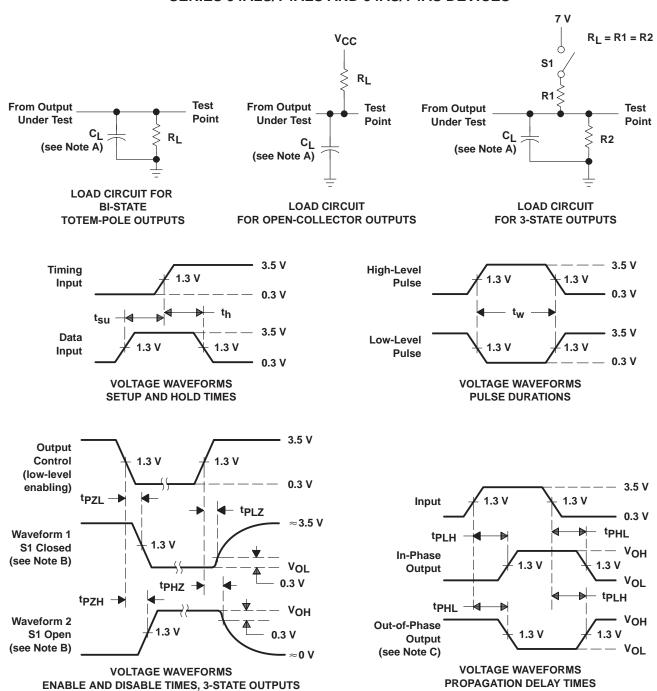
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 C _L = 50 pF R _L = 500 Ω T _A = MIN to	V to 5.5 V, ; o MAX¶	UNIT
t _{PLH}	A or B	V	1	6	
t _{PHL}	AUID		1	6	ns

[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74AS1008AD	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS1008A
SN74AS1008AD.A	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS1008A
SN74AS1008ADE4	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS1008A
SN74AS1008AN	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74AS1008AN
SN74AS1008AN.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74AS1008AN

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

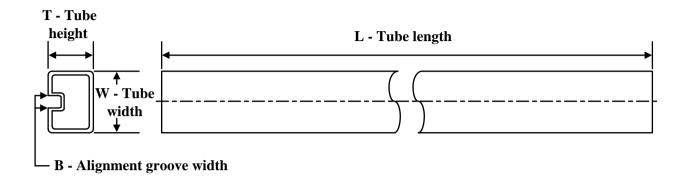
⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE

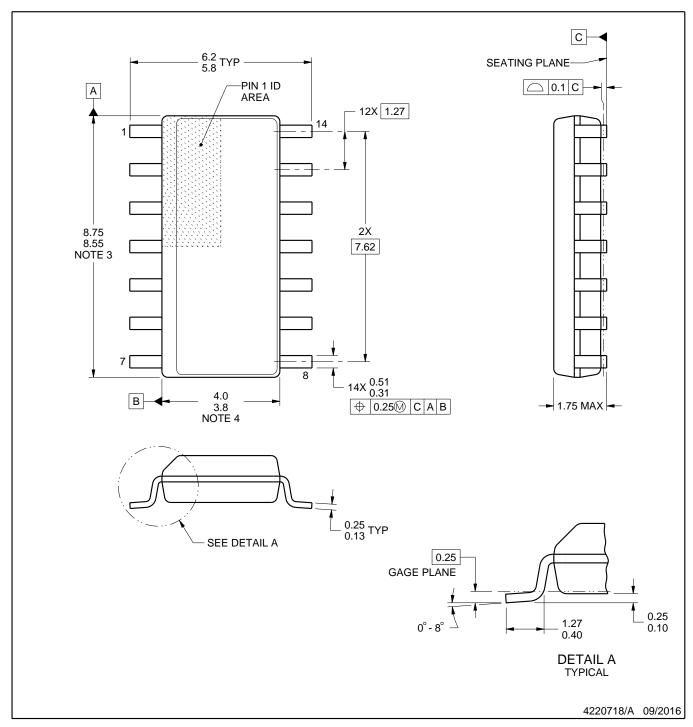


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74AS1008AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74AS1008AD.A	D	SOIC	14	50	506.6	8	3940	4.32
SN74AS1008ADE4	D	SOIC	14	50	506.6	8	3940	4.32
SN74AS1008AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS1008AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS1008AN.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS1008AN.A	N	PDIP	14	25	506	13.97	11230	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

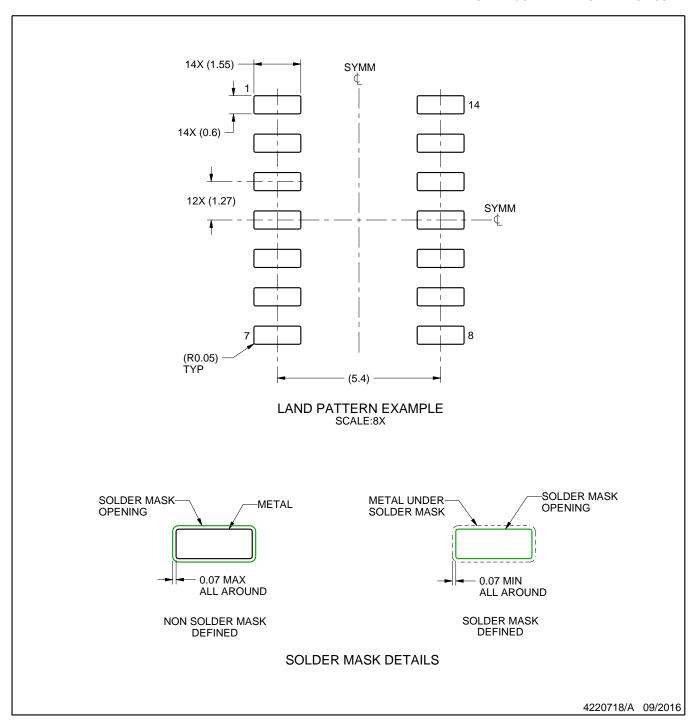
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



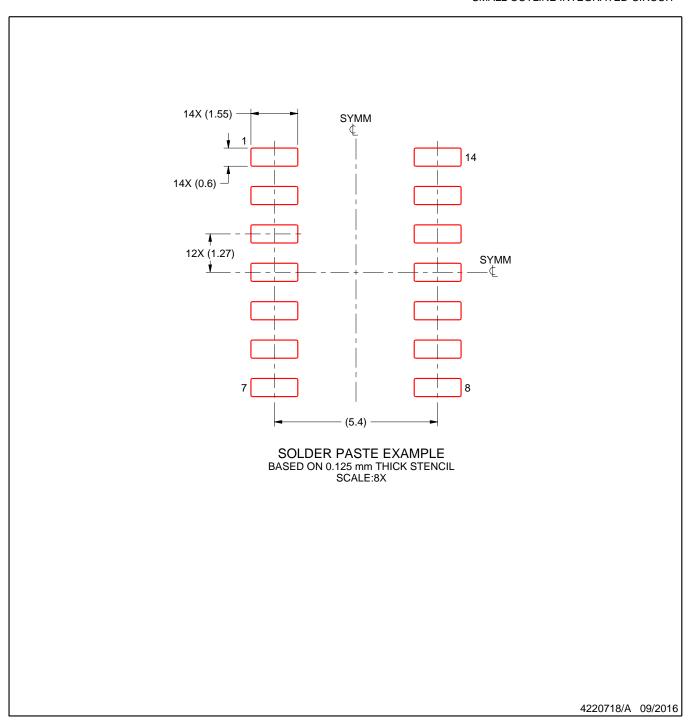
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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